

# CGHV59070

70 W, 4.4 - 5.9 GHz, 50 V, RF Power GaN HEMT

## Description

Wolfspeed's CGHV59070 is an internally matched gallium nitride (GaN) high electron mobility transistor (HEMT). The CGHV59070, operating from a 50 volt rail, offers a general purpose, broadband solution to a variety of RF and microwave applications. The good efficiency, high gain and wide bandwidth capabilities make the CGHV59070 ideal for linear applications such as wireless infrastructure and for compressed amplifier circuits. The transistor is available in a flange and pill package.



Package Type: 440224, 440170  
PN's: CGHV59070F, CGHV59070P

## Features

- 4.4 - 5.9 GHz Operation
- 90 W  $P_{out}$  typical at 50 V
- 14 dB Power Gain
- 55% Drain Efficiency
- Internally Matched

## Applications

- Wireless Infrastructure
- Marine Radar
- Weather Monitoring
- Air Traffic Control
- Maritime Vessel Traffic Control
- Port Security
- Troposcatter Communications
- Beyond Line of Sight - BLOS

## Typical Performance Over 4.8 - 5.9 GHz ( $T_c = 25^\circ\text{C}$ )

Parameter	4.8 GHz	5.0 GHz	5.2 GHz	5.4 GHz	5.6 GHz	5.8 GHz	5.9 GHz	Units
Power Gain at 50 V	13.7	14.2	14.5	14.6	14.3	13.7	13.3	dB
Output Power at 50 V	84	93	101	102	95	84	76	W
Drain Efficiency at 50 V	55	56	57	56	54	50	48	%

Notes:

<sup>1</sup> Measured in CGHV59070F-AMP (838269) under 100μs pulse width, 10% duty cycle,  $P_{in} = 35.5 \text{ dBm}$  (3.5 W)



Large Signal Models Available for ADS and MWO



## Absolute Maximum Ratings (not simultaneous) at 25°C Case Temperature

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	V <sub>DSS</sub>	150	V	25°C
Gate-to-Source Voltage	V <sub>GS</sub>	-10, +2		
Storage Temperature	T <sub>STG</sub>	-65, +150	°C	
Operating Junction Temperature	T <sub>J</sub>	225		
Maximum Forward Gate Current	I <sub>GMAX</sub>	10.4	mA	25°C
Maximum Drain Current <sup>1</sup>	I <sub>DMAX</sub>	6.3	A	
Soldering Temperature <sup>2</sup>	T <sub>S</sub>	245	°C	
Screw Torque	τ	40	in-oz	
Thermal Resistance, Junction to Case <sup>3</sup>	R <sub>θJC</sub>	2.99	°C/W	85°C, CW @ P <sub>DISS</sub> = 57 W
Thermal Resistance, Junction to Case <sup>3</sup>		0.85		85°C, 100μs, 10% Duty Cycle @ P <sub>DISS</sub> = 70 W
Case Operating Temperature <sup>4</sup>	T <sub>C</sub>	-40, +150	°C	

Notes:

<sup>1</sup> Current limit for long term, reliable operation

<sup>2</sup> Refer to the Application Note on soldering at [wolfspeed.com/rf/document-library](http://wolfspeed.com/rf/document-library)

<sup>3</sup> Measured for the CGHV59070F at P<sub>DISS</sub> = 57.6 CW or P<sub>DISS</sub> = 70 W Pulsed

<sup>4</sup> See also, the Power Dissipation De-rating Curve on Page 8

## Electrical Characteristics (T<sub>C</sub> = 25°C)

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	-3.8	-2.8	-2.3	V <sub>DC</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10.4 mA
Saturated Drain Current <sup>2</sup>	I <sub>DS</sub>	6.8	9.7	—	A	V <sub>DS</sub> = 6.0 V, V <sub>GS</sub> = 2.0 V
Drain-Source Breakdown Voltage	V <sub>BR</sub>	125	—	—	V <sub>DC</sub>	V <sub>GS</sub> = -8 V, I <sub>D</sub> = 10.4 mA
<b>RF Characteristics<sup>3</sup> (T<sub>C</sub> = 25°C, F<sub>0</sub> = 5.2 - 5.9 GHz unless otherwise noted)</b>						
Small Signal Gain at 5.2 GHz	G <sub>SS</sub>	15.55	17	—	dB	V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 0.15 A, P <sub>IN</sub> = 10 dBm
Output Power at 5.2 GHz	P <sub>OUT</sub>	75.9	100	—	W	V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 0.15 A, P <sub>IN</sub> = 35.5 dBm
Output Power at 5.55 GHz				—		
Output Power at 5.9 GHz		62.4	77	—		
Drain Efficiency at 5.2 GHz	η	50	55	—	% V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 0.15 A, P <sub>IN</sub> = 35.5 dBm	V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 0.15 A, P <sub>IN</sub> = 35.5 dBm
Drain Efficiency at 5.55 GHz		46	54	—		
Drain Efficiency at 5.9 GHz		40	48	—		
Power Gain at 5.2 GHz	G <sub>P</sub>	—	14.5	—	dB	
Output Mismatch Stress	VSWR	—	—	5 : 1	Ψ	No damage at all phase angles, V <sub>DD</sub> = 50 V, I <sub>DQ</sub> = 0.15 A, P <sub>IN</sub> = 35.5 dBm Pulsed
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>GS</sub>	—	36	—	pF	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = -8 V, f = 1 MHz
Output Capacitance	C <sub>DS</sub>	—	109	—		
Feedback Capacitance	C <sub>GD</sub>	—	0.26	—		

Notes:

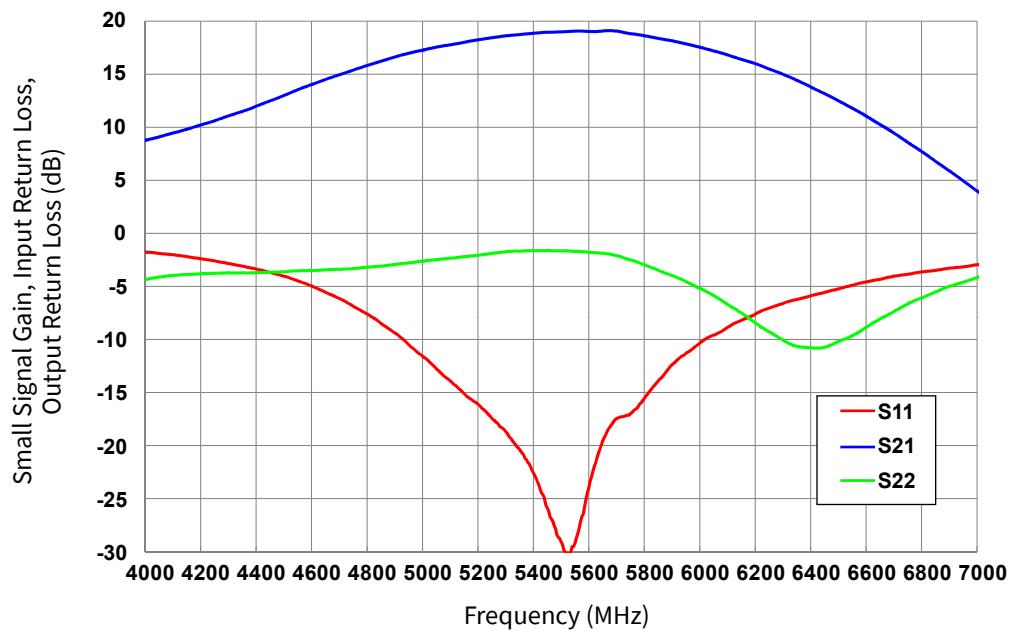
<sup>1</sup> Measured on wafer prior to packaging

<sup>2</sup> Scaled from PCM data

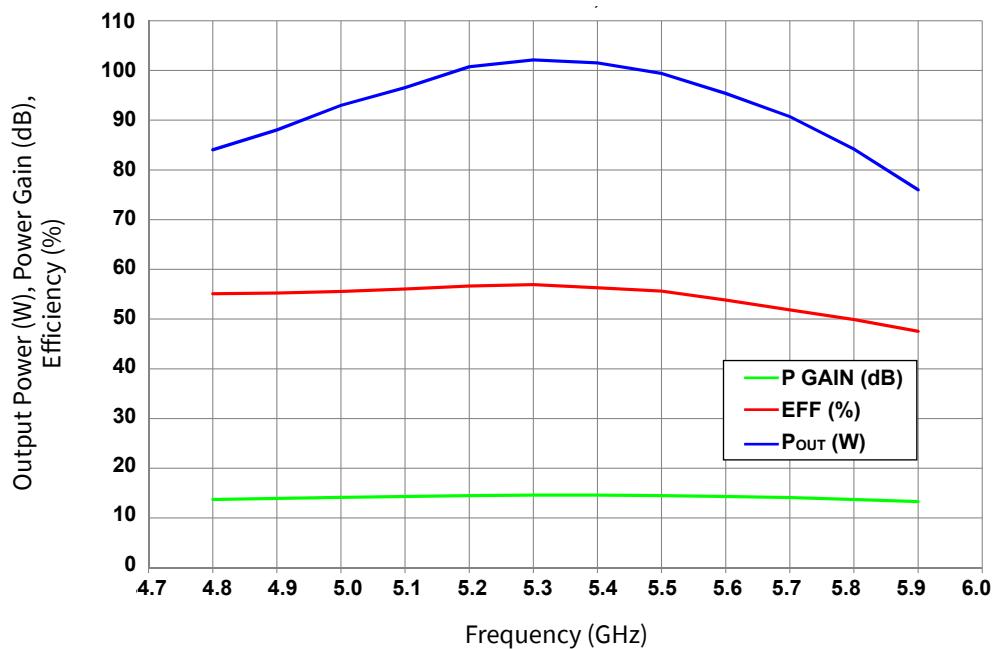
<sup>3</sup> Measured in CGHV59070F-AMP

<sup>4</sup> Drain Efficiency = P<sub>OUT</sub>/P<sub>DC</sub>

## Typical Performance

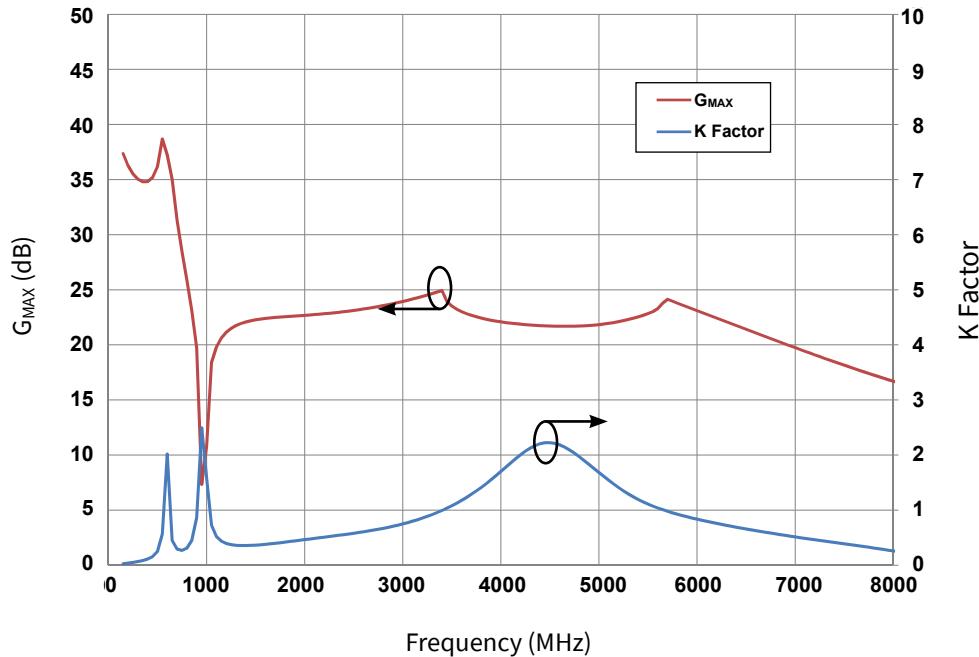


**Figure 1.** Small Signal Gain and Return Losses of the CGHV59070-AMP vs Frequency  
 $V_{DD} = 50$  V,  $I_{DQ} = 150$  mA

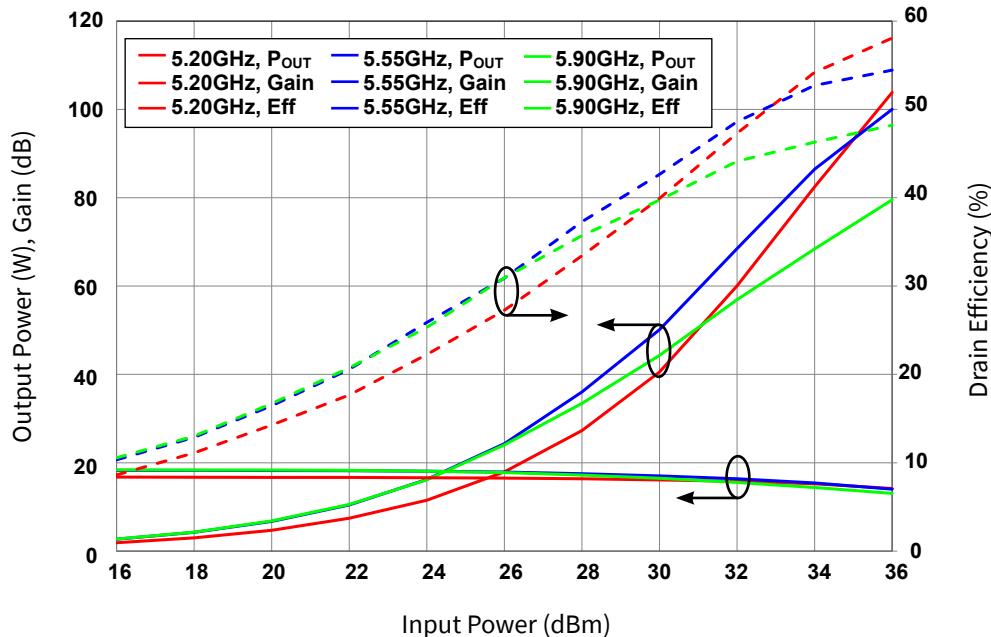


**Figure 2.** Power Gain, Drain Efficiency, and Output Power vs Frequency measured in Amplifier Circuit CGHV59070P-AMP  
 $V_{DD} = 50$  V,  $I_{DQ} = 150$  mA,  $P_{IN} = 35.5$  dBm, Pulse Width = 100μsec, Duty Cycle = 10%

## Typical Performance

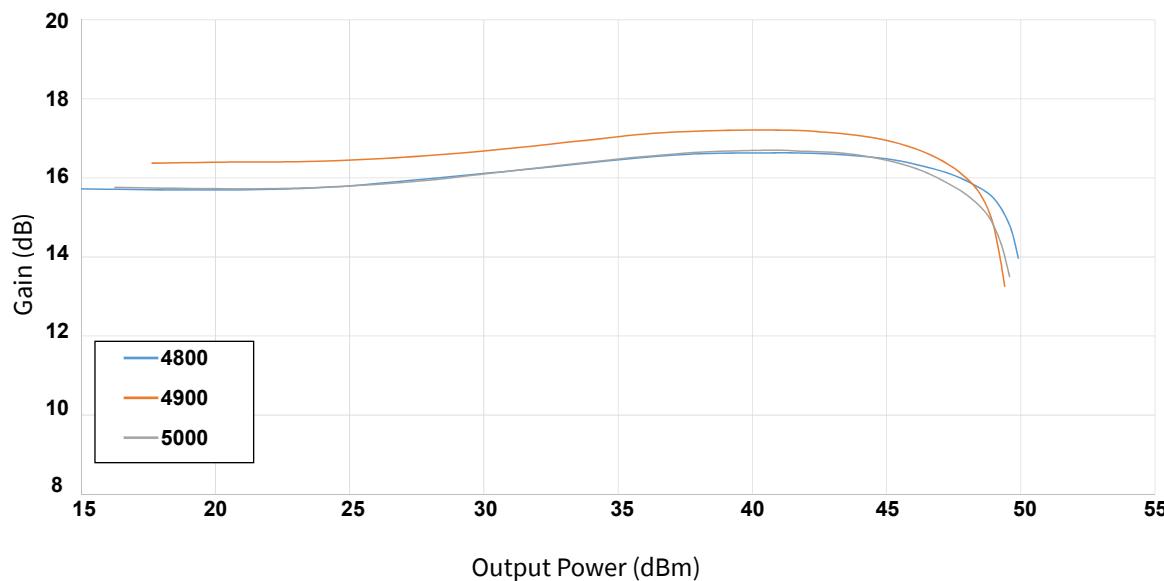


**Figure 3.** Maximum Available Gain and K Factor of the CGHV59070  
 $V_{DD} = 50$  V,  $I_{DQ} = 150$  mA

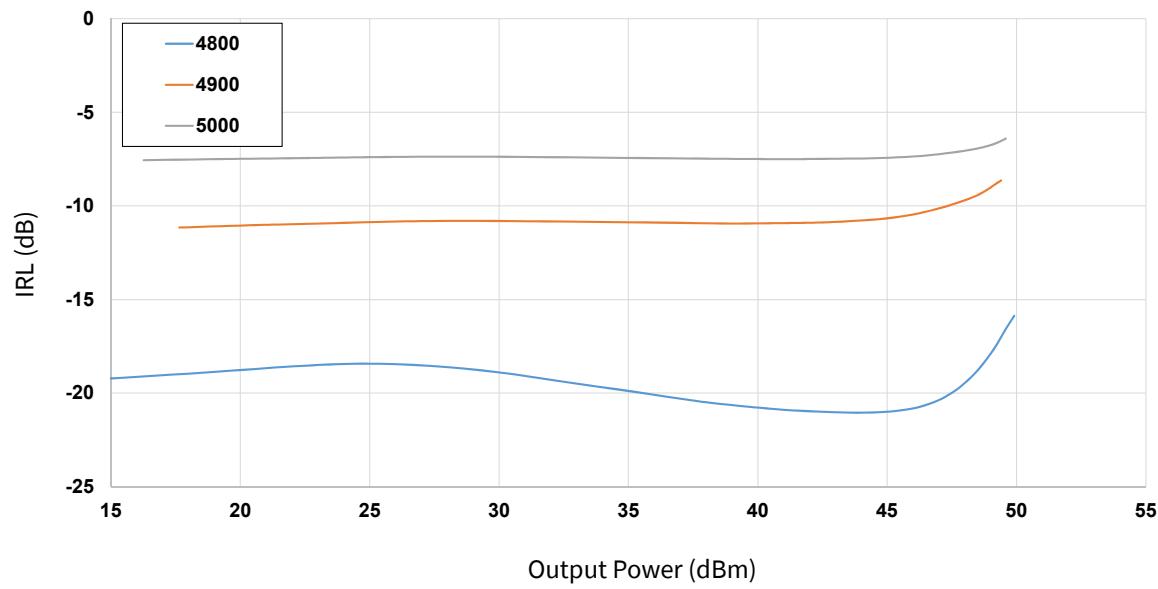


**Figure 4.** Power Gain, Drain Efficiency, and Output Power vs Input Power of the CGHV59070  
 $V_{DD} = 50$  V,  $I_{DQ} = 150$  mA, Pulse Width = 100 $\mu$ sec, Duty Cycle = 10%

## Typical Performance

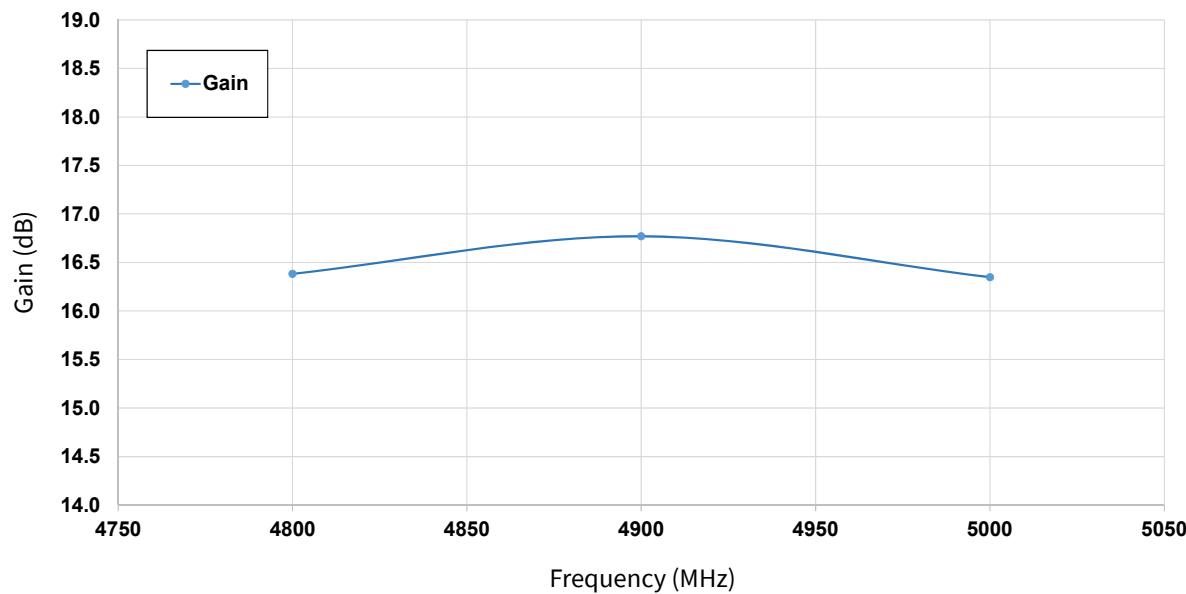


**Figure 5.** Gain vs Output Power Measured in CGHV59070F-AMP4  
 $V_{DD} = 50$  V,  $I_{DQ} = 75$  mA

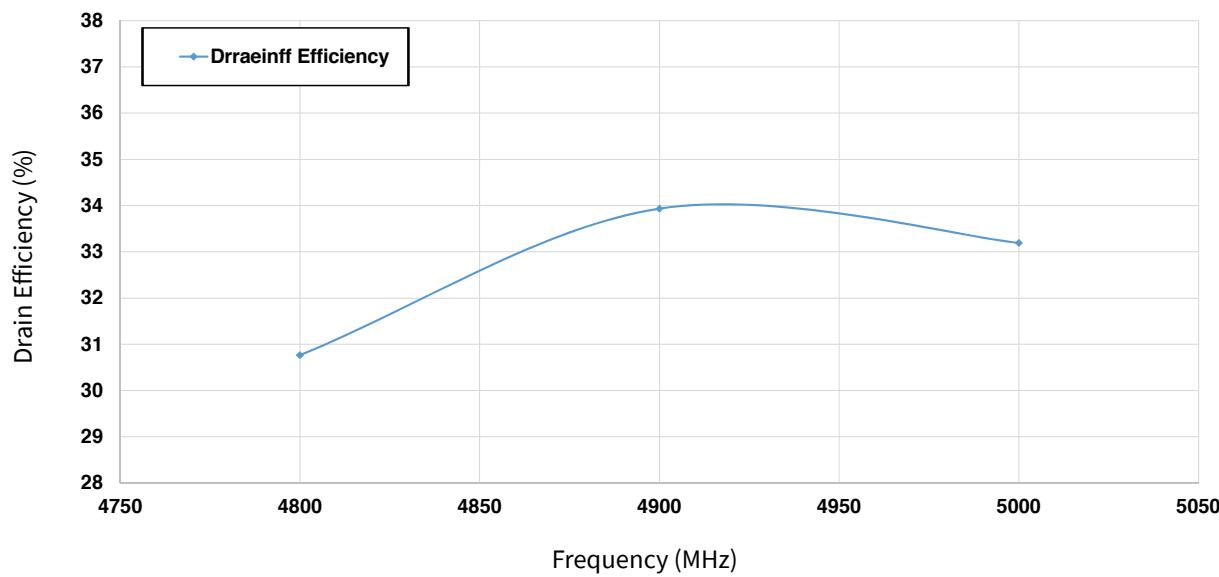


**Figure 6.** Input Return Loss vs Output Power Measured in CGHV59070F-AMP4  
 $V_{DD} = 50$  V,  $I_{DQ} = 75$  mA

## Typical Performance



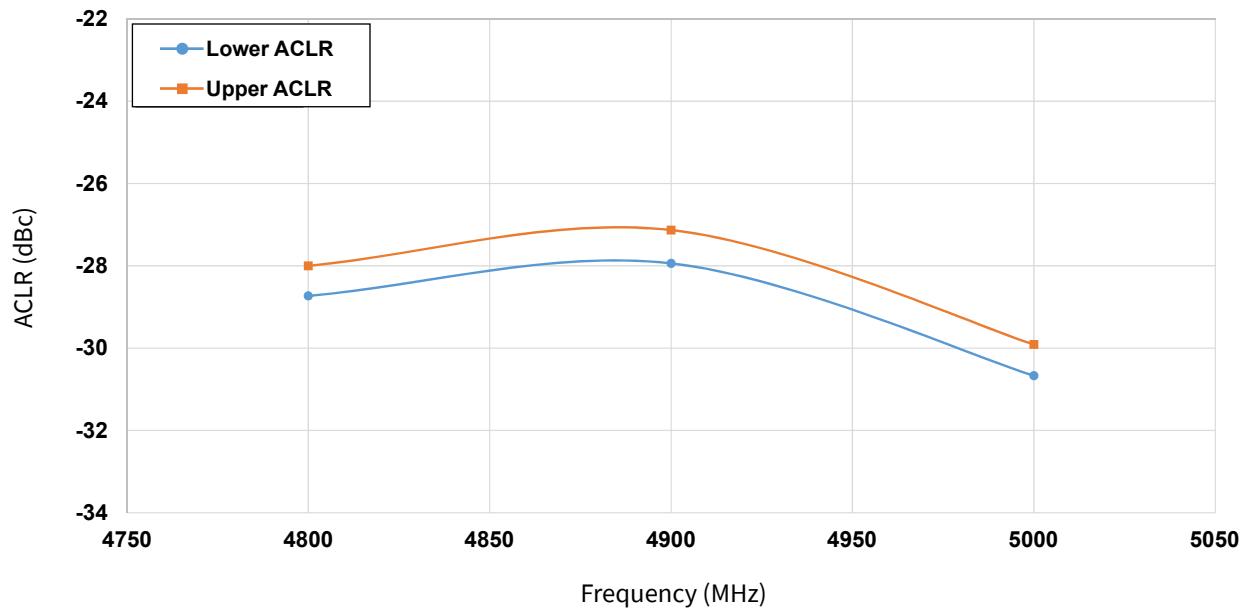
**Figure 7.** Gain vs Frequency Measured in CGHV59070F-AMP4  
 $V_{DD} = 50$  V,  $I_{DQ} = 75$  mA,  $P_{OUT} = 42$  dBm



**Figure 8.** Drain Efficiency vs Frequency Measured in CGHV59070F-AMP4  
 $V_{DD} = 50$  V,  $I_{DQ} = 75$  mA,  $P_{OUT} = 42$  dBm



## Typical Performance

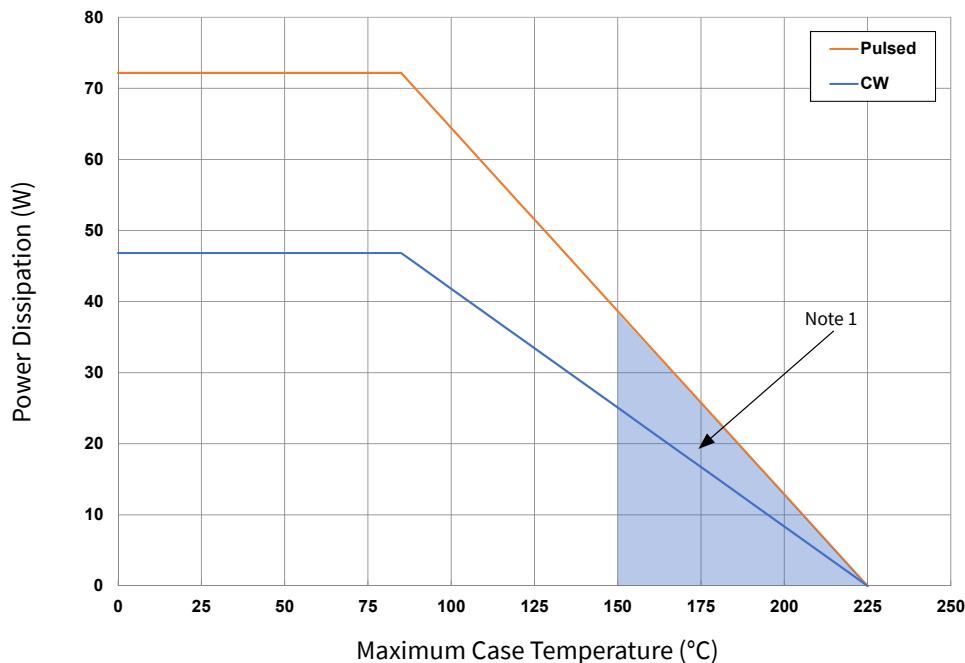


**Figure 9.** ACLR vs Frequency Measured in CGHV59070F-AMP4  
 $V_{DD} = 50$  V,  $I_{DQ} = 75$  mA,  $P_{OUT} = 42$  dBm, WCDMA 7.5 dB PAR Signal

## Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Classification Level	Test Methodology
Human Body Model	HBM	1B	ANSI/ESDA/JEDEC JS-001 Table 3	JEDEC JESD22 A114-D
Charge Device Model	CDM	C3	ANSI/ESDA/JEDEC JS-002 Table 3	JEDEC JESD22 C101-C

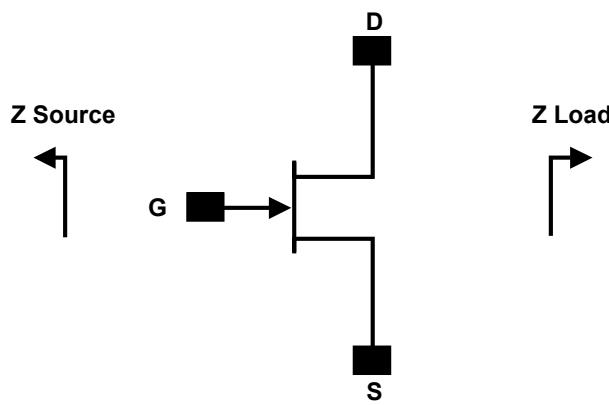
## CGHV59070 Power Dissipation De-Rating Curve, Pulsed & CW (Pulsed Width = 100µs, Duty Cycle = 10%)



Note

<sup>1</sup> Area exceeds Maximum Case Temperature (See Page 2).

## Simulated Source and Load Impedances

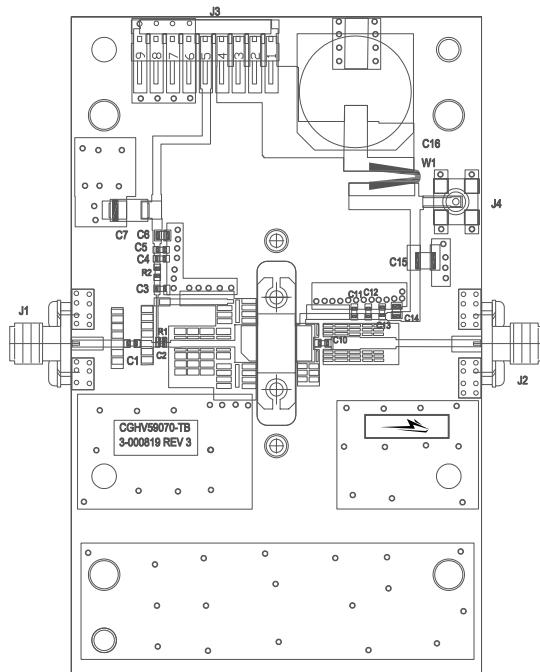


Notes:

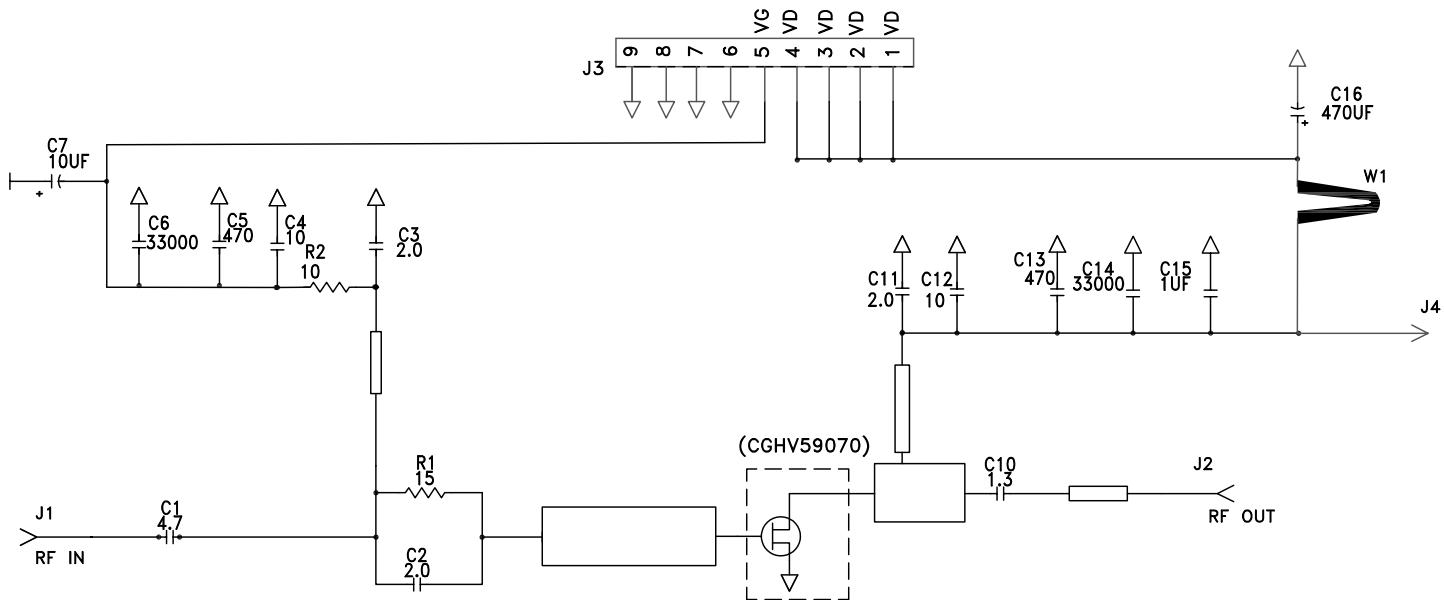
<sup>1</sup>  $V_{DD} = 50$  V,  $I_{DQ} = 150$  mA in the 440224 package<sup>2</sup> Optimized for power gain,  $P_{SAT}$  and PAE<sup>3</sup> When using this device at low frequency, series resistors should be used to maintain amplifier stability

Frequency (MHz)	Z Source	Z Load
4400	2.6 - j12.9	14.0 - j6.9
4600	3.8 - j14.2	15.0 - j6.7
4800	5.8 - j15.3	16.0 - j7.0
5000	8.8 - j15.4	16.7 - j8.0
5200	8.8 - j14.7	17.1 - j9.1
5300	8.5 - j14.5	16.9 - j10.0
5400	8.1 - j14.2	16.5 - j10.7
5500	7.8 - j13.9	15.4 - j11.4
5600	7.5 - j13.6	15.4 - j12.0
5700	7.2 - j13.3	14.6 - j12.5
5800	6.9 - j13.3	13.8 - j12.8
5900	6.6 - j12.7	12.9 - j13.1

## CGHV59070-AMP Demonstration Amplifier Circuit Outline

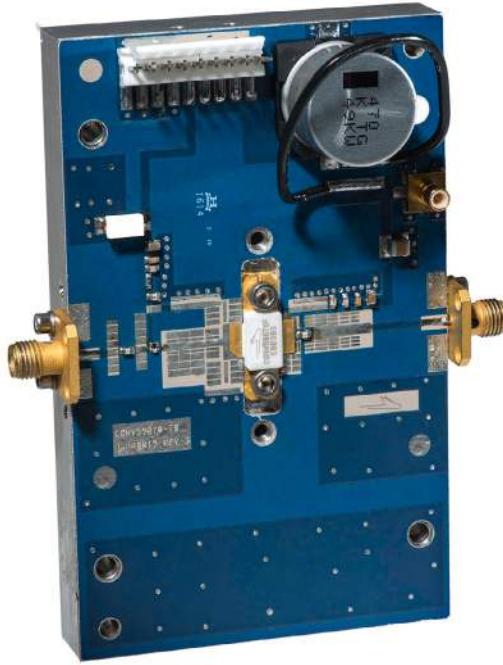


## CGHV59070-AMP Demonstration Amplifier Circuit Schematic





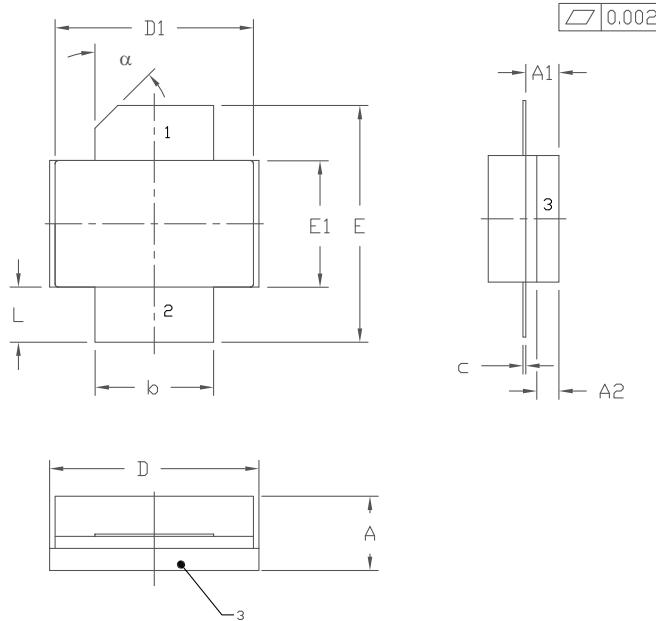
## CGHV59070-AMP Demonstration Amplifier Circuit



## CGHV59070-AMP Demonstration Amplifier Circuit Bill of Materials

Designator	Description	Qty
R1	RES, 15, OHM, +/- 1%, 1/16W, 0402	1
R2	RES, 1/16W, 0603, 1%, 10.0 OHMS	1
C1	CAP, 4.7pF, +/- 0.1pF, 0603, ATC600S	1
C10	CAP, 1.3pF, +/- 0.1pF, 0603, ATC600S	1
C3, C11	CAP, 2.0pF, +/- 0.1pF, 0603, ATC600S	1
C2	CAP, 2.0pF, +/- 0.05pF, 0402, ATC600L	1
C4, C12	CAP, 10pF, +/- 5%, 0603, ATC600S	2
C5, C13	CAP, 470pF, 5%, 100V, 0603, X	2
C6, C14	CAP, 33000pF, 0805, 100V, X7R	2
C15	CAP, 1.0μF, 100V, 10%, X7R, 1210	1
C7	CAP, 10μF 16V TANTALUM	1
W1	CABLE, 18 AWG, 4.2 inch	1
C16	CAP, 470μF, 20%, 80V, ELECT, SMD Size K	1
J1, J2	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE	2
J3	HEADER RT>PLZ .1CEN LK 9POS	1
J4	CONNECTOR; SMB, Straight, JACK, SMD	1
—	Taconic RF-35, PCB, 20 mil	1
Q1	CGHV59070	1

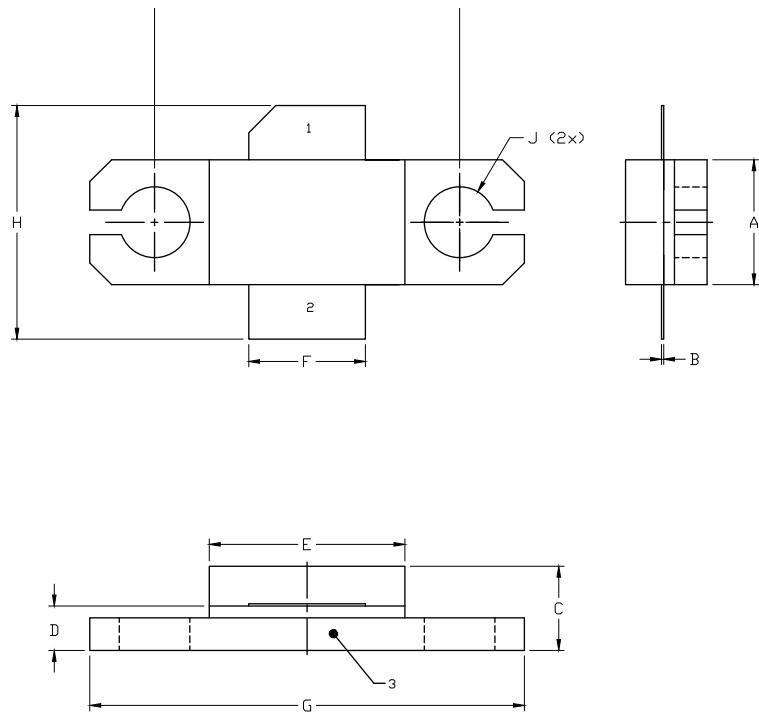
## Product Dimensions CGHV59070P (Package Type – 440170)



DIM	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.125	0.145	3.18	3.68	
A1	0.057	0.067	1.45	1.70	
A2	0.035	0.045	0.89	1.14	
b	0.210	0.220	5.33	5.59	2x
c	0.004	0.006	0.10	0.15	2x
D	0.375	0.385	9.53	9.78	
D1	0.355	0.365	9.02	9.27	
E	0.400	0.460	10.16	11.68	
E1	0.225	0.235	5.72	5.97	
L	0.085	0.115	2.16	2.92	2x
α	45° REF		45° REF		

PIN 1. GATE  
PIN 2. DRAIN  
PIN 3. SOURCE

## Product Dimensions CGHV59070F (Package Type – 440224)



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.225	0.235	5.72	5.97
B	0.004	0.006	0.10	0.15
C	0.145	0.165	3.68	4.19
D	0.077	0.087	1.96	2.21
E	0.355	0.365	9.02	9.27
F	0.210	0.220	5.33	5.59
G	0.795	0.805	20.19	20.45
H	0.400	0.460	10.16	11.68
J	∅ .130		3.30	
k	0.562		14.27	

PIN 1. GATE  
PIN 2. DRAIN  
PIN 3. SOURCE



## Part Number System

**CGHV59070F**



**Table 1.**

Parameter	Value	Units
Upper Frequency <sup>1</sup>	5.9	GHz
Power Output	70	W
Package	Flange/Pill	—

Note:

<sup>1</sup> Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

**Table 2.**

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz



## Product Ordering Information

Order Number	Description	Unit of Measure	Image
CGHV59070F	GaN HEMT	Each	A close-up photograph of a GaN HEMT die mounted in a gold-colored metal lead frame. The die is rectangular with a flat top surface. The lead frame has two large circular pads at the bottom and two smaller circular pads on the sides.
CGH59070P	GaN HEMT	Each	A close-up photograph of a GaN HEMT die mounted on a copper-colored metal substrate. The die is rectangular with a flat top surface. The substrate has a small red printed code "CGHV59070P C96933S".
CGHV59070F-AMP	Test board with GaN HEMT installed	Each	A photograph of a blue printed circuit board (PCB) labeled "TEST BOARD". It features various electronic components, including a central integrated circuit package, resistors, capacitors, and connectors. Two SMA connectors are visible on the right side of the board.

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